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(54) **ELECTROCONDUCTIVE MEMBER, ELECTRONIC DEVICE, AND METHOD FOR MANUFACTURING ELECTROCONDUCTIVE MEMBER**

(57) A conductive member, an electronic device, and a method for manufacturing the conductive member, in which stable characteristics can be obtained are provided. According to one embodiment of the invention, a conductive member includes a first layer including a metal nanowire, a second layer including a polythiophene member, and a third layer including a graphene member including a graphene skeleton. The second layer is provided between the metal nanowire and the third layer.

FIG. 1A

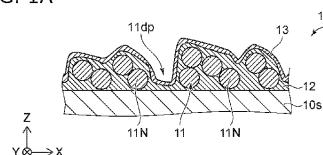
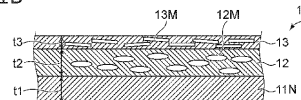


FIG. 1B



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